



Materials Declaration Form

IPC Form Type *	1752 Distribute	Version	2
Sectionals *	Material Info Manufacturing Info	Subsectionals *	A-D <i>* : Required Field</i>

Supplier Information			
Company Name *	STMicroelectronics	Response Date *	2020-07-30
Company Unique ID	NL 008751171801		
Authorized Representative *	Antonella Lanzafame	Representative Title	AMS Material Declaration Champion
Representative Phone *	Refer to Supplier Comment section	Representative Email *	Refer to Supplier Comment section
Supplier Comment	Online Technical Support - STMicroelectronics : http://www.st.com/web/en/support/support.html		

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Supplier Acceptance * true Legal Declaration * Standard
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Product				
Mfr Item Number	Mfr Item Name	Version	Mfr Site	Date
LSM6DS3TR-C	77NN*MV7UACC	A	CA2A	2020-07-30
	Amount	UoM	Unit type	ST ECOPACK Grade
	13.2	mg	Each	ECOPACK® 2

Manufacturing information				
J-STD-020 MSL Rating	Classification Temp	Nbr of Reflow Cycles		
3	260	3		
bulk Solder Termination	Terminal Plating	Terminal Base Alloy	Comment	
NAC	Nickel/Palladium/Gold (Ni/Pd/Au)	Copper Alloy	0	



Package Designator	Size	Nbr of instances	Shape	
LGA	2.50.863	14	Flat	
Comment	VFLGA2.5X3X.86 14L P.5 L.475X.25			

QueryList : RoHS Directive 2011/65/EU-July 2011 Annex II amended by Directive 2015/863-March 2015	
Query	Response
1 - Product(s) meets EU RoHS requirement without any exemptions	false
2 - Product(s) meets EU RoHS requirements except lead in solder and this usage may qualify under the lead in solder '7b' exemption (other selected exemptions may apply)	true
3 - Product(s) meets EU RoHS requirements by application of the selected exemption(s)	true
4 - Product(s) does not meet EU RoHS requirements and is not under exemptions	false
Exemption Id.	Description
7c-I	7c-I-Electrical and electronic components containing lead in a glass or ceramic other than dielectric ceramic in capacitors, e.g. piezoelectric devices, or in a glass or ceramic matrix compound

QueryList : ELV directive : 2000/53/EC amended 2020/363_ March 2020	
Query	Response
1 - Product(s) meets EU ELV requirement without any exemptions	false
2 - Product(s) meets EU ELV requirements by application of the selected exemption(s)	true
Exemption Id.	Description
10a	10a - Electrical and electronic components which contain lead in a glass or ceramic, in a glass or ceramic matrix compound, in a glass-ceramic material, or in a glass-ceramic matrix compound.

QueryList : California Prop65 list, dated 3rd January 2020			
Query			Response
1 - The product does not contain identified substance from California Prop 65 List, no exposure to consumers is foreseen			false
2 - The product is containing below substance(s) from California Prop 65 List, no exposure to consumers is foreseen			false
Substance	amount in product (mg)	Application	ppm in product
Nickel	0.105	alloy	7955
Lead	0.192	passivation	14576
Lead-Borate Glass	0.319	passivation	24167

u9				
Query				Response
1 - Product(s) does not contain REACH Substances Of Very High Concern above the limits per the definition within REACH				true
CategoryLevel_Name	CategoryLevel_Threshold	amount in product (mg)	Application	ppm in product
2 - Product(s) does not contain REACH Substances Of Very High Concern in any Homogeneous Material above the limits per the definition within REACH				true
CategoryLevel_Name	CategoryLevel_Threshold	Amount in Homogeneous Material (mg)	Application - Homogeneous Material	ppm in Homogeneous Material

QueryList : Korea Chemical Control Act_ 27 Dec 2017 update				
Query				Response
The Product does contain at least one of the substances listed in Chemical Control Act				false
Substance present in device Homogeneous Material				
Substance	Homogeneous Material impacted	Concentration in the material(%)	Application Purpose	

Material Composition Declaration						Mfr Item Name	77NN'MV7UACC		13-2009	1000002.0	1000006.0					
Homogeneous Material	Material Group	Mass	UoM	Level	Substance Category	Substance	CAS	Exempt	Mass	UoM	Concentration in homogeneous material (ppm)	Concentration in product (ppm)				
Dies	M-011 Other inorganic materials	6.676	mg	supplier	die	Silicon(Si)	7440-21-3		6.207	mg	929748	470227				
				supplier	metallisation	Aluminum(Al)	7429-90-5		0.015	mg	2247	1136				
				supplier	metallisation	Copper(Cu)	7440-50-8		0.018	mg	2696	1364				
				supplier	metallisation	Cobalt(Co)	7440-48-4		0.013	mg	1947	985				
				supplier	metallisation	Tantalum(Ta)	7440-25-7		0.004	mg	599	303				
				supplier	metallisation	Titanium (Ti)	7440-32-6		0.006	mg	899	455				
				supplier	metallisation	Tungsten(W)	7440-33-7		0.002	mg	300	152				
				supplier	metallisation	Zirconium(Zr)	7440-67-7		0.002	mg	300	152				
				supplier	Passivation	Silicon Nitride (SiN)	12033-89-5		0.010	mg	1498	758				
				supplier	passivation	Silicon Oxide	7631-86-9		0.080	mg	11983	6061				
				supplier	JIG-R & California 65	glass	Lead-Borate Glass	65997-18-4	7c-I-Electrical and electri	0.319	mg	47783	24167			
				Substrate	M-015 Other organic materials	2.64	mg	supplier	laminata	Fiber glass	65997-17-3		0.393	mg	148864	29773
								supplier	laminata	Bisphenol F type epoxy resin	9003-36-5		0.219	mg	82955	16591
								supplier	laminata	Bismaleimide (B)	105391-33-1		0.133	mg	50379	10076
supplier	laminata	Triazine (T)	25722-66-1						0.132	mg	50000	10000				
supplier	laminata	Aluminum hydroxide	21645-51-2						0.009	mg	3409	682				
supplier	laminata	Zinc hydroxide	20427-58-1						0.002	mg	758	152				
supplier	laminata	Calcium sulfate	7778-18-9						0.005	mg	1894	379				
supplier	SVHC	laminata	BPA					80-05-7		0.001	mg	379	76			
supplier	laminata	Acrylic resin	9003-01-4						0.193	mg	73106	14621				
supplier	laminata	Barium sulfate	7727-43-7						0.082	mg	31061	6212				
supplier	laminata	epoxy resin	85954-11-6						0.071	mg	26894	5379				
supplier	laminata	Talc	14807-96-6						0.049	mg	18561	3712				
supplier	laminata	Aromatic hydrocarbon	64742-94-5						0.022	mg	8333	1667				
supplier	laminata	Methoxymethylethoxy propanol	34590-94-8						0.054	mg	20455	4091				
supplier	laminata	Acetate compound	112-15-2						0.054	mg	20455	4091				
supplier	laminata	DPMA	88917-22-0						0.011	mg	4167	833				
supplier	laminata	Diphenyl-trimethylbenzoyl phosphine oxide	75990-60-8						0.008	mg	3030	606				
supplier	M-004 Copper and its alloys	metallisation	Copper(Cu)					7440-50-8		1.078	mg	408333	81667			
supplier	M-006 Nickel and its alloys	metallisation	Nickel(Ni)					7440-02-0		0.105	mg	39773	7955			
supplier	metallisation	Gold(Au)	7440-57-5						0.019	mg	7197	1439				
Die attach	M-015 Other organic materials	0.201	mg					supplier	tape	Epoxy resin	25068-38-6		0.127	mg	631841	9621
				supplier	tape	Polypropylene	9003-07-0		0.004	mg	19900	303				
				supplier	tape	epoxy resin	29690-82-2		0.020	mg	99502	1515				
				supplier	tape	Propenoate polymer	538311-13-6		0.040	mg	199005	3030				
supplier	tape	Bisphenol A diglycidyl ether	1675-54-3		0.010	mg	49751	758								
Bonding wire	M-008 Precious metals	0.154	mg	supplier	wire	Gold(Au)	7440-57-5		0.152	mg	967013	11515				
				supplier	wire	Palladium(Pd)	7440-05-3		0.002	mg	12987	152				
Encapsulation	M-015 Other organic materials	3.529	mg	supplier	mold compound	Silica vitreous	60676-86-0		3.194	mg	905072	241970				
				supplier	mold compound	Epoxyde bisphenol A resin	25068-38-6		0.088	mg	24936	6667				
				supplier	mold compound	Epoxy resin	proprietary		0.141	mg	39955	10682				
				supplier	mold compound	Phenol Resin	proprietary		0.088	mg	24936	6667				
supplier	mold compound	Carbon black	1333-86-4		0.018	mg	5101	1364								